Universal Semiconductor Technology, Inc. (USTI)

3236 Scott Boulevard

Not CalARP Regulated

Approximately 0.45 mile from site

Haz Mat Inventory from 4/11 HMBP

✓ BL#107183

C 07-22-11 JN

5/26/11 ✓DK

UNIFIED PROGRAM CONSOLIDATED FORM
FACILITY INFORMATION
BUSINESS ACTIVITIES

I. FACILITY IDENTIFICATION

FACILITY ID # (Agency Use Only)	7 0 0 7 6 5	1.	EPA ID # (Hazardous Waste Only) CAT080033939	2.

BUSINESS NAME (Same as Facility Name or DBA - Doing Business As) 3.

Universal Semiconductor Technology, Inc

II. ACTIVITIES DECLARATION

NOTE: If you check YES to any part of this list, please submit the Business Owner/Operator Identification page (OES Form 2730).

Does your facility…		If Yes, please complete these pages of the UPCF…
A. HAZARDOUS MATERIALS Have on site (for any purpose) hazardous materials at or above 55 gallons for liquids, 500 pounds for solids, or 200 cubic feet for compressed gases (include liquids in ASTs and USTs); or the applicable Federal threshold quantity for an extremely hazardous substance specified in 40 CFR Part 355, Appendix A or B; or handle radiological materials in quantities for which an emergency plan is required pursuant to 10 CFR Parts 30, 40 or 70?	☒ YES ☐ NO 4.	HAZARDOUS MATERIALS INVENTORY – CHEMICAL DESCRIPTION (OES 2731)
B. UNDERGROUND STORAGE TANKS (USTs) 1. Own or operate underground storage tanks?	☐ YES ☒ NO 5.	UST FACILITY (Formerly SWRCB Form A) UST TANK (one page per tank) (Formerly Form B)
2. Intend to upgrade existing or install new USTs?	☐ YES ☒ NO 6.	UST FACILITY UST TANK (one per tank) UST INSTALLATION - CERTIFICATE OF COMPLIANCE (one page per tank) (Formerly Form C)
3. Need to report closing a UST?	☐ YES ☒ NO 7.	UST TANK (closure portion – one page per tank)
C. ABOVE GROUND PETROLEUM STORAGE TANKS (ASTs) Own or operate ASTs above these thresholds: ---any tank capacity is greater than 660 gallons, or ---the total capacity for the facility is greater than 1,320 gallons?	☐ YES ☒ NO 8.	NO FORM REQUIRED TO CUPAs
D. HAZARDOUS WASTE 1. Generate hazardous waste?	☒ YES ☐ NO 9.	EPA ID NUMBER – provide at the top of this page
2. Recycle more than 100 kg/month of excluded or exempted recyclable materials (per HSC §25143.2)?	☐ YES ☒ NO 10.	RECYCLABLE MATERIALS REPORT (one per recycler)
3. Treat hazardous waste on site?	☐ YES ☒ NO 11.	ONSITE HAZARDOUS WASTE TREATMENT – FACILITY (Formerly DTSC Forms 1772) ONSITE HAZARDOUS WASTE TREATMENT – UNIT (one page per unit) (Formerly DTSC Forms 1772 A,B,C,D and L)
4. Treatment subject to financial assurance requirements (for Permit by Rule and Conditional Authorization)?	☒ YES ☐ NO 12.	CERTIFICATION OF FINANCIAL ASSURANCE (Formerly DTSC Form 1232)
5. Consolidate hazardous waste generated at a remote site?	☐ YES ☒ NO 13.	REMOTE WASTE / CONSOLIDATION SITE ANNUAL NOTIFICATION (Formerly DTSC Form 1196)
6. Need to report the closure/removal of a tank that was classified as hazardous waste and cleaned onsite?	☐ YES ☒ NO 14.	HAZARDOUS WASTE TANK CLOSURE CERTIFICATION (Formerly DTSC Form 1249)

E. LOCAL REQUIREMENTS 15.

(You may also be required to provide additional information by your CUPA or local agency.)

3736 Scott

RECEIVED

MAY 24 2011

S.C.F.D.

UNIFIED PROGRAM CONSOLIDATED FORM
FACILITY INFORMATION

BUSINESS OWNER/OPERATOR IDENTIFICATION

I. IDENTIFICATION

FACILITY ID # (Agency Use Only)	1.	BEGINNING DATE 100.	ENDING DATE 101.
BUSINESS NAME (Same as FACILITY NAME or DBA – Doing Business As) 3. Universal Semiconductor Technology, Inc		BUSINESS PHONE 102. (408) 986-5060	
BUSINESS SITE ADDRESS 103. 3236 Scott Blvd			
CITY 104. Santa Clara	CA	ZIP CODE 105. 95054	
DUN & BRADSTREET 106. 13-163-5765		SIC CODE (4 digit #) 107. 3674	
COUNTY 108. Santa Clara			
BUSINESS OPERATOR NAME 109. Owen Wu		BUSINESS OPERATOR PHONE 110. (408) 986-5060 Ext 109	

II. BUSINESS OWNER

OWNER NAME 111. Mr. BAO HUA ZHENG	OWNER PHONE 112. (408) 986-5060	
OWNER MAILING ADDRESS 113. 3236 Scott Blvd		
CITY 114. Santa Clara	STATE 115. CA	ZIP CODE 116. 95054

III. ENVIRONMENTAL CONTACT

CONTACT NAME 117. Tarek Husseini	CONTACT PHONE 118. (408) 986-5060 Ext 105	
CONTACT MAILING ADDRESS 119. 3236 Scott Blvd		
CITY 120. Santa Clara	STATE 121. CA	ZIP CODE 122. 95054

IV. EMERGENCY CONTACTS

-PRIMARY-	-SECONDARY-
NAME 123. Rick Nakatsu	NAME 128. Tarek Husseini
TITLE 124. Operation MGR	TITLE 129. Facilities Eng
BUSINESS PHONE 125. (408) 986-5060 Ext 110	BUSINESS PHONE 130. (408) 986-5060 Ext 105
24-HOUR PHONE* 126. (408) 590-0910 CELL	24-HOUR PHONE* 131. (408) 771-5436 CELL
PAGER # 127.	PAGER # 132.

ADDITIONAL LOCALLY COLLECTED INFORMATION: 133.

Property Owner: Mission West Properties, Inc Karl Berg Phone No.: (408) 725-0700

Billing Address: 10050 Bandley Dr
Cupertino, CA. 95014

Certification: Based on my inquiry of those individuals responsible for obtaining the information, I certify under penalty of law that I have personally examined and am familiar with the information submitted and believe the information is true, accurate, and complete.

SIGNATURE OF OWNER/OPERATOR OR DESIGNATED REPRESENTATIVE R. Nakatsu	DATE 134. 04/25/11	NAME OF DOCUMENT PREPARER 135. Tarek Husseini
NAME OF SIGNER (print) 136. Rick Nakatsu	TITLE OF SIGNER 137. Operation MGR	

* See Instructions on next page.

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-1	FG		Forming Gas	Nitrogen	90%	7727-37-9	M	G	V	100	100	0.25		CF	365	R	2	4	F	P				1-1
				Hydrogen	10%	1333-74-0																		
							Total			100				CF										
1-1	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	337	200	337		CF	365	L	2	4	F	P				1-1
							Total			337				CF										
1-1	NFG		Argon	Argon	100%	7440-37-1	P	G	V	338	336	338		CF	365	L	2	4		P				1-1
1-1	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-1
							Total			640				CF										
1-1	FL		2-Propanol	Isopropy I Alcohol	100%	67-63-0	P	L	V	13	0.5	3 oz		Gal	365	N	1	4	F					1-1
1-1	FL		Acetone	Acetone	100%	67-64-1	P	L	V	13	0.5	3 oz		Gal	365	N	1	4	F					1-1
1-1	FL		Liquid Flux 5RMA	Rosin	40-50%	65997-05-9	M	L	V	0.25	0.13	3 oz		Gal	365	N	1	4	F			I		1-1
				Alcohols	30-40%	71076-86-3																		
				Methyl Ethyl Ketone	10-30%	78-93-3																		
							Total			2.25				Gal										
1-1	CORR		Epo-Tek 353ND	Bisphhenol F	75-100%	28064-14-4	M	L	V	0.0035	0.0017	0.0002		CF	365	N	1	4				I		1-1
				Imidazole	20-40%	288-32-4																		
							Total			0.0035				CF										
1-1	NR		Epoxy Adhesive 2216 part A	Aliphatic Polymer Diamine	40-70%	68911-25-1	M	S	V	0.0004	0.0002	0.0002		CF	365	N	1	4				I		1-1
				Kaolin	30-60%	1332-58-7																		
				Amorphous Silica	5-10%	67762-90-7																		
1-1	NR		Epoxy Adhesive 2216 part B	Epoxy Resin	60-100%	25068-38-6	M	S	V	0.0004	0.0002	0.0002		CF	365	N	1	4				I		1-1
				Kaolin	10-30%	1332-58-7																		
1-1	NR		Ablebond 84-1LMI	Silver	70-85%	7440-22-4	M	S	V	0.2000	0.1000	0.0004		CF	365	N	1	4				I	D	1-1
				Aromatic Amine	1-10%	Proprietary																		
				Epoxy Resin	5-25%	Proprietary																		
1-1	NR		Ablebond 958-7	Silver	70-90%	7440-22-4	M	S	V	0.0040	0.0020	0.0001		CF	365	N	1	4				I	D	1-1
				Epoxy Resin	1-20%	Proprietary																		
				1,4-Bis(2,3-epoxpropoxy)butane	1-10%	2425-79-8																		
1-1	NR		3145 RTV Mil-A-46146 Adhesive/Sealant	Methyltrimethoxysilane	7-13%	1185-55-3	P	S	V	0.0003	0.0001	0.0003		CF	365	N	1	4				I	D	1-1
1-1	NR		Abletherm 2600G	Silver	75-95%	7440-22-4	P	S	V	0.0017	0.0009	0.00002		CF	365	N	1	4				I	D	1-1
1-1	NR		Epo-Tek H65-175MP	Bisphhenol F	45-70%	28064-14-4	M	S	V	0.0042	0.0021	0.0004		CF	365	N	1	4				I	D	1-1
				1,4 Butanediol Diglycidyl Ether	10-30%	2425-79-8																		
							Total			0.21				CF										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-1	NR		Ablefilm 564A	Epoxy Resin	60-100%	Proprietary	M	Film	V	0.63	0.32	0.63		Lbs	365	N	1	4				I		1-1
				Curing & Hardening agent	5-10%	Proprietary																		
1-1	NR		Epo-Tek H20E Part A	Silver Flake	50-75%	7440-22-4	M	L	V	0.25	0.13	0.25		Lbs	365	N	1	4				I	D	1-1
				Bisphhenol F	30-55%	28064-14-4																		
1-1	NR		Epo-Tek H20E Part B	Silver Flake	70-90%	7440-22-4	P	L	V	0.25	0.13	0.25		Lbs	365	N	1	4				I	D	1-1
1-1	NR		Solder Alloys Containing Lead	Tin	0-100%	7444-31-5	M	S	V	1	0.5	1		Lbs	365	N	1	4				I	D	1-1
				Lead	0-100%	7439-92-1																		
				Antimony	0-100%	7440-36-0																		
				Copper	0-100%	7440-508																		
				Silver	0-100%	7440-22-4																		
				Bismuth	0-100%	7440-69-9																		
				Zinc	0-100%	7440-66-6																		
							Total			2.13				Lbs										
1-1	NR		FC-40 FLUORINERT	Perfluoro Compounds	100%	86508-42-1	P	L	V	15	10	15		Gal	365	P	1	4						1-1
							Total			15				Gal										
1-2	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-2
							Total			304				CF										
1-2	FL		2-Propanol	Isopropy l Alcohol	100%	67-63-0	P	L	V	0.5 3	0.25	3 oz		Gal	365	N	1	4	F					1-2
1-2	FL		Acetone	Acetone	100%	67-64-1	P	L	V	0.5 3	0.25	3 oz		Gal	365	N	1	4	F					1-2
							Total			1				Gal										
1-3	FL		2-Propanol	Isopropy l Alcohol	100%	67-63-0	P	L	V	0.25 3	0.13	3 oz		Gal	365	N	1	4	F					1-3
							Total			0.25				Gal										
1-3	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-3
							Total			304				CF										
1-4	NFG		Argon	Argon	100%	7440-37-1	P	G	V	338	170	338		CF	365	L	2	4		P				1-4
1-4	NFG		Halocarbon12	Dichlorofluoroethane	100%	75-71-8	M	G	V	106	60	106		CF	365	L	2	4		P				1-4
1-4	NFG		Helium	Helium	100%	7440-59-7	P	G	V	1144	600	286		CF	365	L	2	4		P				1-4
1-4	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	912	460	304		CF	365	L	2	4		P				1-4
1-4	NFG		Mixture of Methane & Argon	Argon	90-100%	7440-37-1	M	G	V	338	170	338		CF	365	L	2	4		P				1-4
				Methane	0.001-10%	74-82-8																		
1-4	NFG		SF6	Sulfur Hexafluoride	100%	2551-62-4	M	G	V	48	24	48		CF	365	L	2	4		P				1-4
1-4	NFG		CF4/02	Carbon Tetrafluoride	80%	75-73-0	M	G	V	612	308	308		CF	365	L	2	4		P				1-4
				Oxygen	20%	7782-44-7																		
							Total			3498				CF										
1-4	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	337	170	337		CF	365	L	2	4	F	P				1-4
							Total			337				CF										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-4	NR		Fomblin Y-LVAC	Propene,1,1,2,3,3-hexafluoro	100%	69991-67-9	P	L	V	5	3	5		Gal	365	L	1	4				I		1-4
							Total			5				Gal										
1-5	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-5
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-5	CL		Positive Photo Resist AZ1529 (NOWPAC)	Propylene Glycol Monomethyl ether acetate	66%	000108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-5
				Cresol novolak resin	<30%	117520-84-0																		
1-5	CL		MEGAPOSIT SPR 220 Photo Resist (NOWPAC)	Cresol novolak resin	25 - 30%		M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-5
				Ethyl Lactate	25 - 35%	97-64-3																		
				Anisole	10 -20 %	100-66-3																		
				Diazo photoactive comp.	1 - 10 %																			
				2- Methlyl Butyl Acetate	1 -10 %	624-41-9																		
				n-amyl acetate	1 -10 %	628-63-7																		
				Cresol	< 1 %	1319-77-3																		
				Organic Siloxane Surfactant	< 1 %																			
1-5	CL		JSR IX875 Positive Photo Resist (NOWPAC)	Methyl 3-Methoxypropionate	75-85%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-5
				Phenolic Resin	10-20%	Proprietary																		
1-5	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L	V	10	6	5		Gal	365	F	2	4	F			I		1-5
							Total			14				Gal										
1-5	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I		1-5
							Total			0.25				Gal										
1-5	NR		MF-319 Developer	Surfactant	< 1%		M	L	V	10	5	5		Gal	365	F	2	4				I		1-5
				Tetramethyl Ammonium Hydroxide	2%	75-59-2																		
							Total			10				Gal										
1-6	FG		Forming Gas	Nitrogen	90%	7727-37-9	M	G	V	585	300	195		CF	365	L	2	4	F	P				1-6
				Hydrogen	10%	1333-74-0																		
							Total			585				CF										
1-6	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	304	304		CF	365	L	2	4		P				1-6
							Total			304				CF										
1-7	CORR		Phosphoric Etchant	Water	95%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I	D	1-7
				Hydrogen Peroxide	3%	7722-84-1																		
				Phosphoric Acid	2.5%	7664-38-2																		
1-7	CORR		Iodic Etchant	Water	91%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I	D	1-7
				Hydrochloric Acid	4.5%	764-701-0																		
				Iodic Acid	4.5%	7782-68-5																		
1-7	CORR		Hydrochloric Acid	Hydrochloric Acid	100%	764-701-0	P	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I		1-7
1-7	CORR		Mesa/Gate Etchant	Water	99.0%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I	D	1-7
				Hydrogen Fluoride	0.01%	7664-39-3																		
				Hydrogen Peroxide	0.6%	7722-84-1																		
1-7	CORR		HF Dip (20:1)	Water	97.5%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I	D	1-7
				Hydrogen Fluoride	2.5%	7664-39-3																		
1-7	CORR		Ammonia Dip	Water	97.0%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	N	1	4				I	D	1-7
				Ammonium Hydroxide	3%	1336-21-6																		
1-7	CORR		Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	V	30	30	15		Gal	365	R	1	5						1-7
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
							Total			57				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity		Max Cont Size	Annual Thru-put	Units	Days on Site	Storage			SARA Class					Storage Location
										Max	Avg					Type	Press	Temp	F	P	R	I	D	
1-7	NFG		Argon	Argon	100%	7440-37-1	P	G	V	676	338	338		CF	365	L	2	4		P				1-7
1-7	NFG		Helium	Helium	100%	7440-59-7	P	G	V	286	140	286		CF	365	L	2	4		P				1-7
1-7	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-7
1-7	NFG		SF6	Sulfur Hexafluoride	100%	2551-62-4	P	G	V	48	24	48		CF	365	L	2	4		P				1-7
1-7	NFG		C2F6	Hexafluoroethane	100%	76-16-4	P	G	V	263	130	263		CF	365	L	2	4		P				1-7
1-7	NFG		N2O	Nitrous Oxide	100%	10024-97-2	P	G	V	524	270	524		CF	365	L	2	4		P				1-7
							Total			2101				CF										
1-7	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	674	337	337		CF	365	L	2	4	F	P				1-7
							Total			674				CF										
1-8	NFG		Argon	Argon	100%	7440-37-1	P	G	V	338	170	338		CF	365	L	2	4		P				1-8
1-8	NFG		CF4	Carbon Tetrafluoride	100%	75-73-0	P	G	V	307	150	307		CF	365	L	2	4		P				1-8
1-8	NFG		Helium	Helium	100%	7440-59-7	P	G	V	286	150	286		CF	365	L	2	4		P				1-8
1-8	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-8
							Total			1235				CF										
1-8	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	337	170	337		CF	365	L	2	4	F	P				1-8
							Total			337				CF										
1-9	NR		MF-319 Developer	Surfactant	< 1%		M	L	V	5	5	1		Gal	365	N	1	4				I		1-9
				Tetramethyl Ammonium Hydroxide	2%	75-59-2																		
							Total			5				Gal										
1-9	CORR		Ammonium Hydroxide	Ammonium Hydroxide	30%	1336-21-6	M	L	V	1	1	1		Gal	365	N	1	4				I		1-9
1-9	CORR		Hydrochloric Acid	Hydrochloric Acid	100%	764-701-0	P	L	V	1	1	1		Gal	365	M	1	4				I		1-9
1-9	CORR		Hydrofluoric Acid(20:1)	Hydrogen Fluoride	2.5%	7664-39-3	M	L	V	5	5	1		Gal	365	N	1	4				I	D	1-9
1-9	CORR		Phosphoric Acid	Phosphoric Acid	87%	7664-38-2	P	L	V	1	1	1		Gal	365	N	1	4				I		1-9
							Total			8				Gal										
1-9	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	M	L	V	1	1	1		Gal	365	N	1	4	F		R	I		1-9
							Total			1				Gal										
1-10	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-10
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-10	CL		Positive Photo Resist AZ1529 (NOWPAC)	Propylene Glycol Monomethyl ether acetate	66%	000108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-10
				Cresol novolak resin	<30%	117520-84-0																		
1-10	CL		MEGAPOSIT SPR 220 Photo Resist (NOWPAC)	Cresol novolak resin	25 - 30%		M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-10
				Ethyl Lactate	25 - 35%	97-64-3																		
				Anisole	10 -20 %	100-66-3																		
				Diazo photoactive comp.	1 - 10 %																			
				2- Methyl Butyl Acetate	1 -10 %	624-41-9																		
				n-amyl acetate	1 -10 %	628-63-7																		
				Cresol	< 1 %	1319-77-3																		
				Organic Siloxane Surfactant	< 1 %																			
1-10	CL		JSR IX875 Positive Photo Resist (NOWPAC)	Methyl 3-Methoxypropionate	75-85%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-10
				Phenolic Resin	10-20%	Proprietary																		
1-10	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L	V	5	5	1		Gal	365	N	2	4	F			I		1-10
							Total			9				Gal										
1-10	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I		1-10
							Total			0.25				Gal										
1-11	FG		Silane<2% in Nitrogen	Silane	<2%	7803-62-5	M	G	V	936	468	234		CF	365	L	2	4	F	P				1-11
				Nitrogen	98%	7727-37-9																		
							Total			936				CF										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-11	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	608	304	304		CF	365	L	2	4		P				1-11
							Total			608				CF										
1-12	NFG		Ammonia	Anhydrous Ammonia	100%	7664-41-7	P	G	V	6780	4520	2260		CF	365	L	2	4	F	P		I	D	1-12
1-12	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	304	304		CF	365	L	2	4		P				1-12
							Total			7084				CF										
1-13	CORR		Sulfuric Acid	Sulfuric Acid	30%	7664-93-9	P	L	V	25	15	25		Gal	365	E	1	4	F	P	R	I		1-13
							Total			25				Gal										
1-14	CORR		Sodium Hydroxide 30%	Sodium Hydroxide	30%	1310-73-2	M	L	V	100 250	250	1000		Gal	365	N	1	4						1-14
							Total			250				Gal										
1-15	NH		Hypersperse Antifloulant	No hazardous materials			M	L	V	50	50	50		Gal	365	N	1	4						1-15
1-15	NH		Calcium Chloride	Calcium Chloride	35%	10043-52-4	M	L	V	250	250	1000		Gal	365	N	1	4						1-15
							Total			300				Gal										
1-15	CORR		Sulfuric Acid	Sulfuric Acid	98%	7664-93-9	P	L	V	55	55	55		Gal	365	N	1	4			R	I		1-15
							Total			55				Gal										
1-16	POIS G		Chlorine	Chlorine	100%	7782-50-5	P	G	V	970	250	485		CF	365	L	2	4	F	Y		I	D	1-16
							Total			970				CF										
1-19	CORR		SKASOL 4030	1-Hydroxyethylidene-1	<40%	2809-21-4	M	L	V	55	30	55		Gal	365	E	1	4				I	D	1-19
				Phosphonic Acid	<20%	6419-19-8																		
1-19	CORR		SKASOL MB-H	Sodium Hypochlorite	<20%	7681-52-9	M	L	V	15	10	15		Gal	365	E	1	4				I	D	1-19
1-19	CORR		SKASOL 101-L	Sulfuric Acid	<80%	7664-93-9	P	L	V	15	10	15		Gal	365	E	1	4				I	D	1-19
1-19	CORR		SKASOL microblocide-4	Glutaraldehyde	<20%	111-30-8	M	L	V	15	10	15		Gal	365	E	1	4				I		1-19
							Total			100				Gal										
1-20	CORR		SKASOL MB-H	Sodium Hypochlorite	<20%	7681-52-9	M	L	V	15	10	15		Gal	365	E	1	4				I	D	1-20
1-20	CORR		SKASOL- 460	2-Phosphonobutane -1	<20%	37971-36-1	M	L	V	15	10	15		Gal	365	E	1	4				I	D	1-20
							Total			30				Gal										
1-21	CORR		SKASOL 4030	1-Hydroxyethylidene-1	<40%	2809-21-4	M	L	V	55	30	55		Gal	365	E	1	4				I	D	1-21
				Phosphonic Acid	<20%	6419-19-8																		
1-21	CORR		SKASOL MB-H	Sodium Hypochlorite	<20%	7681-52-9	M	L	V	15	10	15		Gal	365	E	1	4				I	D	1-21
1-21	CORR		SKASOL 101-L	Sulfuric Acid	<80%	7664-93-9	P	L	V	15	10	15		Gal	365	E	1	4				I	D	1-21
1-21	CORR		SKASOL microblocide-4	Glutaraldehyde	<20%	111-30-8	M	L	V	15	10	15		Gal	365	E	1	4				I		1-21
							Total			100				Gal										
1-22	FL		2-Propanol	Isopropy l Alcohol	100%	67-63-0	P	L	V	40	20	1		Gal	365	N	1	4	F					1-22
1-22	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L	V	2	1	0.25		Gal	365	M	1	4	F			I		1-22
1-22	FL		N-Butyl Acetate	N-Butyl Acetate	100%	123-86-4	P	L	V	8	4	1		Gal	365	M	1	4	F					1-22
1-22	FL		Waycoat SC Resist	Xylene	60%	1330-20-7	M	L	V	1	1	1		Gal	365	M	1	4	F				D	1-22
				Polyisoprene	25%	68441-13-4																		1-22
				Ethyl Benzene	15%	100-41-4																		1-22
1-22	FL		Toluene	Methylbenzene, Phenymethane, Toluol	92%	108-88-3	M	L	V	8	4	1		Gal	365	M	1	4	F			I	D	1-22
1-22	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	16	8	1		Gal	365	M	1	4	F					1-22
1-22	FL		Acetone	Acetone	100%	67-64-1	P	L	V	20	10	1		Gal	365	N	1	4	F					1-22
1-22	FL		495 PMMA Series Resist In Chlorobenzene	Monochlorobenzene	88 - 99%	108-90-7	M	L	V	1	0.5	0.25		Gal	365	M	1	4	F			I	D	1-22
				Poly (methylmerhacrylate)	1 -12 %	9011-14-7																		
							Total			96				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity		Max Cont Size	Annual Thru-put	Units	Days on Site	Storage			SARA Class					Storage Location
										Max	Avg					Type	Press	Temp	F	P	R	I	D	
1-24	CL		AZ NMP Rinse	n-methylpyrolidone	100%	872-50-4	P	L	V	12	8	1		Gal	365	N	1	4	F					1-24
1-24	CL		Positive Photo Resist AZ1529	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-24
				Cresol-novolak resin	<30%	117520-84-0																		
1-24	CL		Positive Photo Resist AZ1529 (NOWPAC)	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	2	1	1		Gal	365	N	1	4	F			I	D	1-24
				Cresol-novolak resin	<30%	117520-84-0																		
1-24	CL		Positive Photo Resist AZP 4620	Propylene Glycol Monomethyl ether acetate	59%	108-65-6	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-24
				Cresol-novolak resin	<30%	117520-84-0																		
1-24	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-24
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-24	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	2	1	1		Gal	365	N	1	4	F			I	D	1-24
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-24	CL		JSR IX875 Positive Photo Resist(NOWPAC)	Methyl 3-Methoxyproplonate	75-85%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-24
				Phenolic Resin	10-20%	Proprietary																		
1-24	CL		MEGAPOSIT SPR 220 Photo Resist (NOWPAC)	Cresol novolak resin	25 - 30%		M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-24
				Ethyl Lactate	25 - 35%	97-64-3																		
				Anisole	10 -20 %	100-66-3																		
				Diazo photoactive comp.	1 - 10 %																			
				2- Methlyl Butyl Acetate	1 -10 %	624-41-9																		
				n-amyl acetate	1 -10 %	628-63-7																		
				Cresol	< 1 %	1319-77-3																		
				Organic Siloxane Surfactant	< 1 %																			
1-24	CL		SC Negative Developer WNRD	Isoparaffinic Hydrocarbon	100%	64742-48-9	M	L	V	8	5	1		Gal	365	N	1	4	F			I		1-24
1-24	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L	V	8	4	1		Gal	365	M	1	4	F			I	D	1-24
1-24	CL CORR		NRS EKC1020 Negative Photoresist Remover	Dodecyl Benzene Sulfonic acid	Proprietary	27176-87-0	M	L	V	12	8	1		Gal	365	N	1	4	F			I	D	1-24
				Heavy Aromatic Slovent Naphtha	Proprietary	64742-94-5																		
				Naphthalene	Proprietary	91-20-3																		
							Total			49				Gal										
1-25	CORR		Metex L5-B	Thiourea	10%	62-56-6	M	L	V	5	3	5		Gal	365	N	1	4				I	D	1-25
1-25	CORR		Ammonium Hydroxide	Ammonium Hydroxide	30%	1336-21-6	M	L	V	4	2	1		Gal	365	N	1	4				I	D	1-25
1-25	CORR		Microposit 454 Developer	Pottasium Hydroxide	1 - 2%	1310-58-3	M	L	V	10	5	1		Gal	365	N	1	4				I		1-25
1-25	CORR		Microposit 455 Developer	Pottasium Hydroxide	1 - 2%	1310-58-3	M	L	V	10	5	1		Gal	365	N	1	4				I		1-25
							Total			19				Gal										
1-25	NR		MF-319 Developer	Surfactant	< 1%		M	L	V	20	10	1		Gal	365	N	1	4				I		1-25
				Tetramethyl Ammonium Hydroxide	2%	75-59-2																		
1-25	NR		Suspension Fluid AQUALAP 19-C	No Hazardous Materials				L	V	10	5	5		Gal	365	N	1	4						1-25
							Total			30				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity		Max Cont Size	Annual Thru-put	Units	Days on Site	Storage			SARA Class					Storage Location
										Max	Avg					Type	Press	Temp	F	P	R	I	D	
1-26	CORR		ACT-410 Positive Resist Stripper Discontinue	Morpholinepropanamine-4	30-70%	123-00-2	M	L	V	24	12	1		Gal	365	N	1	4	F			I	D	1-26
				n-methylpyrolidone	30-70%	872-50-4																		
1-26	CORR		B.O.E (6:1 Solution)	Ammonium Fluoride	34%	12125-01-8	M	L	V	8	4	1		Gal	365	N	1	4				I	D	1-26
				Hydrogen Fluoride	7%	7664-39-3																		
1-26	CORR		Nano-Strip	Sulfuric Acid	90%	7664-93-9	M	L	V	4	2	1	6	Gal	365	N	1	4			R	I		1-26
				Peroxymonosulfuric Acid	5%	7722-86-3																		
				Hydrogen Peroxide	1%	7722-84-1																		
1-26	CORR		Hydrochloric Acid	Hydrochloric Acid	100%	764-701-0	P	L	V	4	2	1		Gal	365	M	1	4				I		1-26
1-26	CORR		Hydrofluoric Acid	Hydrogen Fluoride	49%	7664-39-3	P	L	V	3	2	0.125		Gal	365	N	1	4				I	D	1-26
1-26	CORR		Hydrofluoric Acid(20:1)	Hydrogen Fluoride	2.5%	7664-39-3	P	L	V	32	16	1		Gal	365	N	1	4				I	D	1-26
1-26	CORR		Sulfuric Acid	Sulfuric Acid	98%	7664-93-9	P	L	V	8	4	1		Gal	365	N	1	4			R	I		1-26
1-26	CORR		Phosphoric Acid	Phosphoric Acid	87%	7664-38-2	P	L	V	4	2	1		Gal	365	N	1	4				I		1-26
1-26	CORR		CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	V	8	4	1		Gal	365	N	1	4				I		1-26
				Iodine	8%	7553-56-2																		
							Total			95				Gal										
1-26	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	M	L	V	30	20	1		Gal	365	N	1	4	F		R	I		1-26
							Total			30				Gal										
1-27	CL		Diesel 2	Diesel Fiel # 2	100%	68476-34-6	M	L	V	55	30	125		Gal	365	D	1	4	F			I	D	1-27
				Distillates, hydrodesulfurized	0-100%	6472-80-9																		
				Distillates,straight run	0-100%	64741-44-2																		
				Kerosine	0-25%	8008-20-6																		
				Kerosine,hydrodesulfurized	0-25%	64742-81-0																		
				Distillates light caralytic	0-50%	64741-59-9																		
				Naphthalene	0.02-.02%	91-20-3																		
				Total Sulfur	0-.05%	none																		
							Total			55				Gal										
1-28	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	2022	1011	337		CF	365	L	2	4	F	P				1-28
							Total			2022				CF										
1-28	NFG		99%Nitrogen;1% Oxygen	Nitrogen	99%	7727-37-9	M	G	V	464	232	232		CF	365	L	2	4		P				1-28
				Oxygen	1%	7782-44-7																		
1-28	NFG		CF4/O2	Carbon Tetrafluoride	80%	75-73-0	M	G	V	414	414	207		CF	365	L	2	4		P				1-28
				Oxygen	20%	7782-44-7																		
							Total			878				CF										
1-29	NFG		Argon	Argon	100%	7440-37-1	P	G	V	672	336	336		CF	365	L	2	4		P				1-29
1-29	NFG		Helium	Helium	100%	7440-59-7	P	G	V	858	572	286		CF	365	L	2	4		P				1-29
1-29	NFG		Mixture of Methane & Argon	Argon	90-100%	7440-37-1	M	G	V	338	170	338		CF	365	L	2	4		P				1-29
				Methane	0.001-10%	74-82-8																		
1-29	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	1216	912	304		CF	365	L	2	4		P				1-29
1-29	NFG		SF6	Sulfur Hexafluoride	100%	2551-62-4	M	G	V	96	96	48		CF	365	L	2	4		P				1-29
							Total			3180				CF										
1-29	FG		Forming Gas	Nitrogen	90%	7727-37-9	M	G	V	1216	608	304		CF	365	L	2	4	F	P				1-29
				Hydrogen	10%	1333-74-0																		
							Total			1216				CF										
1-30	CL		AZ NMP Rinse	n-methylpyrolidone	100%	872-50-4	P	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-30
							Total			1				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-30	FL		2-Propanol	Isopropyl Alcohol	100%	67-63-0	P	L	V	1	0.5	1		Gal	365	N	1	4	F					1-30
1-30	FL		Acetone	Acetone	100%	67-64-1	P	L	V	1	0.5	1		Gal	365	N	1	4	F					1-30
1-30	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	2	1	1		Gal	365	M	1	4	F					1-30
							Total			4				Gal										
1-30	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	M	L	V	1	0.5	1		Gal	365	N	1	4	F		R	I		1-30
							Total			1				Gal										
1-30	CORR		CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	V	1	0.5	1		Gal	365	N	1	4				I		1-30
				Iodine	8%	7553-56-2																		
1-30	CORR		Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	V	12	9	1		Gal	365	N	1	4						1-30
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
							Total			13				Gal										
1-31	CL		Positive Photo Resist AZP 4620	Propylene Glycol Monomethyl ether acetate	59%	108-65-6	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-31
				Cresol-novolak resin	<30%	117520-84-0																		
							Total			1				Gal										
1-31	FL		Waycoat SC Resist	Xylene	60%	1330-20-7	M	L	V	2	1	1		Gal	365	M	1	4	F				D	1-31
				Polyisoprene	25%	68441-13-4																		
				Ethyl Benzene	15%	100-41-4																		
1-31	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	2	1	1		Gal	365	M	1	4	F					1-31
							Total			4				Gal										
1-32	FG		Forming Gas	Nitrogen	90%	7727-37-9	M	G	V	304	150	304		CF	365	L	2	4	F	P				1-32
				Hydrogen	10%	1333-74-0																		
							Total			304				CF										
1-33	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	1011	337	337		CF	365	L	2	4	F	P				1-33
							Total			1011				CF										
1-34	CL		Positive Photo Resist AZ1529	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-34
				Cresol-novolak resin	<30%	117520-84-0																		
1-34	CL		Positive Photo Resist AZ1529 (NOWPAC)	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-34
				Cresol-novolak resin	<30%	117520-84-0																		
1-34	CL		Positive Photo Resist AZP 4620	Propylene Glycol Monomethyl ether acetate	59%	108-65-6	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-34
				Cresol-novolak resin	<30%	117520-84-0																		
1-34	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-34
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-34	CL		SC Negative Developer WNRD	Isoparaffinic Hydrocarbon	100%	64742-48-9	M	L	V	1	1	1		Gal	365									1-34
1-34	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L	V	5	5	1		Gal	365	M	1	4	F			I	D	1-34
1-34	CL		AZ NMP Rinse	n-methylpyrolidone	100%	872-50-4	P	L	V	4	4	1		Gal	365	N	1	4	F			I	D	1-34
1-34	CL CORR		NRS EKC1020 Negative Photoresist Remover	Dodecyl Benzene Sulfonic acid	Proprietary	27176-87-0	M	L	V	2	2	1		Gal	365	N	1	4	F			I	D	1-34
				Heavy Aromatic Slovent Naphtha	Proprietary	64742-94-5																		
				Naphthalene	Proprietary	91-20-3																		
							Total			16				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-34	FL		2-Propanol	Isopropal Alcohol	100%	67-63-0	P	L	V	3	3	1		Gal	365	N	1	4	F					1-34
1-34	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I		1-34
1-34	FL		N-Butyl Acetate	N-Butyl Acetate	100%	123-86-4	P	L	V	2	2	1		Gal	365	M	1	4	F					1-34
1-34	FL		Waycoat SC Resist	Xylene	60%	1330-20-7	M	L	V	1	1	1		Gal	365	M	1	4	F				D	1-34
				Polyisoprene	25%	68441-13-4																		
				Ethyl Benzene	15%	100-41-4																		
1-34	FL		Toluene	Methylbenzene, Phenymethane, Toluol	92%	108-88-3	M	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-34
1-34	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	2	2	1		Gal	365	M	1	4	F					1-34
1-34	FL		Acetone	Acetone	100%	67-64-1	P	L	V	3	3	1		Gal	365	N	1	4	F					1-34
1-34	FL		495 PMMA Series Resist in Chlorobenzene	Monochlorobenzene	88 - 99%	108-90-7	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I	D	1-34
				Poly (methylmerhacrylate)	1 -12 %	9011-14-7																		
							Total			12.5				Gal										
1-35	NR		MF-319 Developer	Surfactant	< 1%		M	L	V	5	3	1		Gal	365	N	1	4				I		1-35
				Tetramethyl Ammonium Hydroxide	2%	75-59-2																		
							Total			5				Gal										
1-35	CORR		ACT-410 Positive Resist Stripper	Morpholinepropanamine-4	30-70%	123-00-2	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-35
				n-methylpyrolidone	30-70%	872-50-4																		
1-35	CORR		Ammonium Hydroxide	Ammonium Hydroxide	30%	1336-21-6	M	L	V	1	1	1		Gal	365	N	1	4				I	D	1-35
1-35	CORR		B.O.E (6:1 Solution)	Ammonium Fluoride	34%	12125-01-8	M	L	V	2	1	1		Gal	365	N	1	4				I	D	1-35
1-35	CORR		Nano-Strip	Sulfuric Acid	90%	7664-93-9	M	L	V	1	1	1		Gal	365	N	1	4			R	I		1-35
				Peroxymonosulfuric Acid	5%	7722-86-3																		
				Hydrogen Peroxide	1%	7722-84-1																		
1-35	CORR		Hydrochloric Acid	Hydrochloric Acid	100%	764-701-0	P	L	V	1	1	1		Gal	365	M	1	4				I		1-35
1-35	CORR		Hydrofluoric Acid	Hydrogen Fluoride	49%	7664-39-3	P	L	V	0.5	0.5	0.125		Gal	365	N	1	4				I	D	1-35
1-35	CORR		Hydrofluoric Acid(20:1)	Hydrogen Fluoride	2.5%	7664-39-3	M	L	V	4	4	1		Gal	365	N	1	4				I	D	1-35
1-35	CORR		Sulfuric Acid	Sulfuric Acid	98%	7664-93-9	P	L	V	2	2	1		Gal	365	N	1	4			R	I		1-35
1-35	CORR		Phosphoric Acid	Phosphoric Acid	87%	7664-38-2	P	L	V	1	1	1		Gal	365	N	1	4				I		1-35
1-35	CORR		CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	V	2	1	1		Gal	365	N	1	4				I		1-35
				Iodine	8%	7553-56-2																		
							Total			15.5				Gal										
1-35	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	M	L	V	3	3	1		Gal	365	N	1	4	F		R	I		1-35
							Total			3				Gal										
1-36	CL		Waycoat Negative Resist Developer	Organic Solvent	100%		M	L	V	2	1	1		Gal	365	N	1	4						1-36
1-36	CL		Positive Photo Resist AZP 4620	Propylene Glycol Monomethyl ether acetate	59%	108-65-6	M	L	V	1	0.5	1		Gal	365	M	1	4	F			I	D	1-36
1-36	CL		Positive Photo Resist AZ1529	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	1	0.5	1		Gal	365	M	1	4	F			I	D	1-36
				Cresol-novolak resin	<30%	117520-64-0																		
1-36	CL		AZ NMP Rinse	n-methylpyrolidone	100%	872-50-4	P	L	V	2	1	1		Gal	365	N	1	4	F			I	D	1-36
1-36	CL CORR		NRS EKC1020 Negative Photoresist Remover	Dodecyl Benzene Sulfonic acid	Proprietary	27176-87-0	M	L	V	2	2	1		Gal	365	N	1	4	F			I	D	1-36
				Heavy Aromatic Slovent Naphtha	Proprietary	64742-94-5																		
				Naphthalene	Proprietary	91-20-3																		
							Total			8				Gal										
1-36	FL		2-Propanol	Isopropy lalcohol	100%	67-63-0	P	L	V	3	2	1		Gal	365	N	1	4	F					1-36
1-36	FL		Acetone	Acetone	100%	67-64-1	P	L	V	3	2	1		Gal	365	N	1	4	F					1-36
1-36	FL		N-Butyl Acetate	N-Butyl Acetate	100%	123-86-4	P	L	V	3	2	1		Gal	365	M	1	4	F					1-36
1-36	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	1	1	1		Gal	365	M	1	4	F					1-36
							Total			10				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-36	CORR		ACT-410 Positive Resist Stripper	Morpholinepropanamine-4	30-70%	123-00-2	M	L	V	3	1.5	1		Gal	365	N	1	4	F			I	D	1-36
				n-methylpyrolidone	30-70%	872-50-4																		
1-36	CORR		B.O.E (6:1 Solution)	Ammonium Fluoride	34%	12125-01-8	M	L	V	2	1	1		Gal	365	N	1	4				I	D	1-36
				Hydrogen Fluoride	7%	7664-39-3																		
1-36	CORR		CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	V	2	1	1		Gal	365	N	1	4				I		1-36
				Iodine	8%	7553-56-2																		
1-36	CORR		Hydrofluric Acid	Hydrogen Fluoride	49%	7664-39-3	P	L	V	0.5	0.25	0.125		Gal	365	N	1	4				I	D	1-36
1-36	CORR		Microposit 454 Developer	Potassium Hydroxide	1 - 2%	1310-58-3	M	L	V	4	2	1		Gal	365	N	1	4				I		1-36
1-36	CORR		Microposit 455 Developer	Potassium Hydroxide	1 - 2%	1310-58-3	M	L	V	4	2	1		Gal	365	N	1	4				I		1-36
1-36	CORR		Sulfuric Acid	Sulfuric Acid	98%	7664-93-9	P	L	V	2	1	1		Gal	365	N	1	4			R	I		1-36
1-36	CORR		20:1 / H2O : Sulfuric Acid	Sulfuric Acid	5%	7664-93-9	P	L	V	1	1	1		Gal	365	R	2	4			R	I		1-36
1-36	CORR		Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	V	8	8	6		Gal	365	R	1	5						1-36
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
							Total			26.5				Gal										
										.75														
1-36	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	P	L	V	0.5	0.5	0.75		Gal	365	R	1	5	F		R	I		1-36
1-36	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	P	L	V	2	1	1		Gal	365	N	1	4	F		R	I		1-36
1-36	OXY		20:1 / H2O : Hydrogen Peroxide	Hydrogen Peroxide	2%	7722-84-1	P	L	V	1	1	1		Gal	365	R	2	4	F		R	I		1-36
1-36	OXY		Nitric Acid	Nitric Acid	70%	7607-37-2	P	L	V	1	1	1		Gal	365	M	1	4				I		1-36
							Total			4.5				Gal										
1-37	CL		AZ NMP Rinse	n-methylpyrolidone	100%	872-50-4	P	L	V	3	1.5	1		Gal	365	M	2	4	F			I	D	1-37
1-37	CL		AZ NMP Rinse (SSEC)	n-methylpyrolidone	100%	872-50-4	P	L	V	15	7.5	1		Gal	365	F	2	4	F			I	D	1-37
							Total			18				Gal										
1-37	FL		Acetone	Acetone	100%	67-64-1	P	L	V	1	0.75	1		Gal	365	R	1	4	F					1-37
1-37	FL		2-Propanol	Isopropal alcohol	100%	67-63-0	P	L	V	2	1.5	1		Gal	365	R	1	4	F					1-37
1-37	FL		2-Propanol (SSEC)	Isopropal alcohol	100%	67-63-0	P	L	V	8	5	1		Gal	365	F	2	4	F					1-37
							Total			11				Gal										
1-37	CORR		Nano-Strip	Sulfuric Acid	90%	7664-93-9	M	L	V	1	1	1		Gal	365	N	1	4			R	I		1-37
				Peroxymonosulfuric Acid	5%	7722-86-3																		
				Hydrogen Peroxide	1%	7722-84-1																		
1-37	CORR		CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	V	2	1	1		Gal	365	N	1	4				I		1-37
				Iodine	8%	7553-56-2																		
1-37	CORR		Hydrofluoric Acid (HF)	Hydrogen Fluoride	49%	7664-39-3	P	L	V	1	1	1		Gal	365	N	1	4				I	D	1-37
1-37	CORR		Ammonium Hydroxide	Ammonium	30%	1336-21-6	M	L	V	1	1	1		Gal	365	R	1	4				I	D	1-37
1-37	CORR		Phosphoric Acid	Phosphoric Acid	87%	7664-38-2	P	L	V	1	1	1		Gal	365	N	1	4				I		1-37
1-37	CORR		Acetic Acid	Acetic Acid	100%	64-19-7	P	L	V	1	1	1		Gal	365	M	1	4	F			I	D	1-37
1-37	CORR		Hydrochloric Acid	Hydrochloric Acid	100%	7647-01-0	P	L	V	1	1	1		Gal	365	N	1	4						1-37
1-37	CORR		Mesa/Gate Etchant	Water	99.0%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	R	1	4				I	D	1-37
				Hydrogen Fluoride	0.01%	7664-39-3																		
				Hydrogen Peroxide	0.6%	7722-84-1																		
1-37	CORR		HF Dip (20:1)	Water	97.5%	7732-18-5	M	L	V	4.5	4.5	4.5		Gal	365	R	1	4				I	D	1-37
				Hydrogen Fluoride	2.5%	7664-39-3																		
1-37	CORR		Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	V	5	5	3		Gal	365	R	1	5						1-37
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
							Total			22				Gal										
1-37	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	P	L	V	1	1	1		Gal	365	R	1	5	F		R	I		1-37
1-37	OXY		Hydrogen Peroxide	Hydrogen Peroxide	30%	7722-84-1	P	L	V	1	1	1		Gal	365	N	1	4	F		R	I		1-37
							Total			2				Gal										
1-37	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	1011	600	337		CF	365	L	2	4	F	P				1-37
							Total			1011				CF										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		VW	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-5	CL	214	Mixed Solvent Waste	Propylene Glycol Monomethyl ether acetate	60-80%	108-65-6	M	L	W	10	5	10	See Waste 1 23	Gal	365	F	2	4	F			I	D	1-5
				Cresol novolak resin	5-10%	Proprietary																		
				Diazo photoactive comp.	1-5%	Proprietary																		
							Total			10				Gal										
1-17	CORR	791	Corrosive Liquid	Hydroflouric Acid	5%	7664-39-3	M	L	W	100	100	400		Gal	365	A	1	4				I	D	1-17
				Acetic Acid	2%	64-19-7																		
				Ammonium Fluoride	2%	12125-01-8																		
				Water	91%																			
							Total			100				Gal										
1-18	CORR	135	CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	W	55	20	55	110	Gal	365	E	1	4				I		1-18
				Iodine	6%	7553-56-2																		
1-18	CL CORR	791	NRS EKC1020 Negative Photoresist Remover	Dodecyl Benzene Sulfonic acid	Proprietary	27176-87-0	M	L	W	55	30	55	250	Gal	365	E	1	4	F			I	D	1-18
				Heavy Aromatic Slovent Naphtha	Proprietary	64742-94-5																		
				Naphthalene	Proprietary	91-20-3																		
1-18	CORR	135	Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	W	15	10	15	60	Gal	365	E	1	4						1-18
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
1-18	CORR	135	Metex L5-B	Thiourea	10%	62-56-6	M	L	W	15	10	15	20	Gal	365	E	1	4				I	D	1-18
							Total			140				Gal										
1-23	FL	214	Mixed Solvent Waste	Acetone	10-30%	67-64-1	M	L	W	55	55	55	1004	Gal	365	D	1	4	F			I	D	1-23
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	10-30%	872-50-4																		
				Toluene	5-20%	108-88-3																		
				Xylene	1-10%	1130-20-7																		
				n-Butyl Acetate	1-10%	123-86-4																		
				Propylene Glycol Monomethyl ether acetate	1-10%	108-65-6																		
				Gamma Butrylactone	1-5%	872-50-4																		
				Chorolbenzene	1-5%	108-90-7																		
							Total			55				Gal										
1-33	FL	214	Mixed Solvent Waste	Acetone	10-30%	67-64-1	M	L	W	10	5	10	See Waste 1 23	Gal	365	G	1	4	F					1-33
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	5-20%	872-50-4																		
				Xylene	5-20%	1130-20-7																		
				Isoparaffinic Hydrocarbon	5-20%	64742-48-9																		
				n-Butyl Acetate	5-20%	123-86-4																		
				Propylene Glycol Monomethyl ether acetate	1-10%	108-65-6																		
							Total			10				Gal										
1-37	FL	214	Mixed Solvent Waste	Acetone	5-20%	67-64-1	M	L	W	10	5	10	See Waste 1 23	Gal	365	G	1	4	F					1-37
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	30-50%	872-50-4																		
							Total			10														
1-37	CORR	135	Metex L5-B	Thiourea	10%	62-56-6	M	L	W	1	1	1	20	Gal	365	R	1	5				I	D	1-37
							Total			1														
1-38	CL	214	Mixed Solvent Waste	Toluene	10-30%	108-88-3	M	L	W	10	5	10	See Waste 1-23	Gal	365	G	1	4	F			I	D	1-38
				Xylene	10-30%	1130-20-7																		
				Propylene Glycol Monomethyl ether acetate	50-70%	108-65-6																		
				Methyl 3-Methoxypropionate	1-5%	9/3/3852																		
				Chorolbenzene	1-2%	108-90-7																		
				Ethyl Lactate	1-5%	97-64-3																		
							Total			10				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State	V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-37	NR		Fomblin Y-LVAC	Propene,1,1,2,3,3-hexafluoro	100%	69991-67-9	P	L V	5	3	5		Gal	365	L	1	4				I		1-37
							Total		5				Gal										
1-38	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Cresol novolak resin	<30%																		
				Cresol	<0.9%	1319-77-3																	
				Diazo photoactive comp.	1 - 10%																		
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																	
1-38	CL		Positive Photo Resist AZ1529 (NOWPAC)	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Cresol-novolak resin	<30%	117520-84-0																	
1-38	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L V	5	3	5		Gal	365	F	2	4	F			I	D	1-38
1-38	CL		JSR IX875 Positive Photo Resist (NOWPAC)	Methyl 3-Methoxypropionate	75-85%	108-65-6	M	L V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Phenolic Resin	10-20%	Proprietary																	
1-38	CL		MEGAPOSIT SPR 220 Photo Resist (NOWPAC)	Cresol novolak resin	25 - 30%		M	L V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Ethyl Lactate	25 - 35%	97-64-3																	
				Anisole	10 -20 %	100-66-3																	
				Diazo photoactive comp.	1 - 10 %																		
				2- Methyl Butyl Acetate	1 -10 %	624-41-9																	
				n-amyl acetate	1 -10 %	628-63-7																	
				Cresol	< 1 %	1319-77-3																	
				Organic Siloxane Surfactant	< 1 %																		
							Total			9			Gal										
1-38	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L V	0.25	0.25	0.25		Gal	365	M	1	4	F			I		1-38
1-38	FL		495 PMMA Series Resist In Chlorobenzene	Monochlorobenzene	88 - 99%	108-90-7	M	L V	0.25	0.25	0.25		Gal	365	M	1	4	F			I	D	1-38
				Poly (methylmerhacrylate)	1 -12 %	9011-14-7	P	L V	1	0.5	1		Gal	365	R	1	4	F			I	D	1-38
1-38	FL		Toluene	Toluene	92%	108-88-3	P	L V	1	0.5	1		Gal	365	R	1	4	F					1-38
1-38	FL		Xylene	Xylene	100%	1330-20-7	P	L V	1	0.5	1		Gal										
							Total			2.5			Gal										
1-38	NR		Fomblin Y-LVAC	Propene,1,1,2,3,3-hexafluoro	100%	69991-67-9	P	L V	5	3	5		Gal	365	L	1	4				I		1-38
1-38	NR		MF-319 Developer	Tetramethyl Ammonium Hydroxide	2%	75-59-2	M	L V	5	3	5		Gal	365	F	2	4				I		1-38
							Total			10			Gal										
1-38	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G V	337	200	337		CF	365	L	2	4	F	P				1-38
							Total		337				CF										
1-39	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G V	304	150	304		CF	365	L	2	4		P				1-39
							Total		304				CF										
1-39	FL		2-Propanol	Isopropy l Alcohol	100%	67-63-0	P	L V	3 0.5	0.25	3 oz		Gal	365	N	1	4	F					1-39
1-39	FL		Acetone	Acetone	100%	67-64-1	P	L V	3 0.5	0.25	3 oz		Gal	365	N	1	4	F					1-39
							Total		1				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity Max	Quantity Avg	Max Cont Size	Annual Thru-put	Units	Days on Site	Storage Type	Storage Press	Storage Temp	SARA Class F	SARA Class P	SARA Class R	SARA Class I	SARA Class D	Storage Location
1-5	CL	214	Mixed Solvent Waste	Propylene Glycol Monomethyl ether acetate	60-80%	108-65-6	M	L	W	10	5	10	See Waste 1 23	Gal	365	F	2	4	F			I	D	1-5
				Cresol novolak resin	5-10%	Proprietary																		
				Diazo photoactive comp.	1-5%	Proprietary																		
							Total			10				Gal										
1-17	CORR	791	Corrosive Liquid	Hydroflouric Acid	5%	7664-39-3	M	L	W	100	100	400		Gal	365	A	1	4				I	D	1-17
				Acetic Acid	2%	64-19-7																		
				Ammonium Fluoride	2%	12125-01-8																		
				Water	91%																			
							Total			100				Gal										
1-18	CORR	135	CGE-100 Gold Etch	Potassium Iodide	26%	7681-11-0	M	L	W	55	20	55	110	Gal	365	E	1	4				I		1-18
				Iodine	8%	7553-56-2																		
1-18	CL CORR	791	NRS EKC1020 Negative Photoresist Remover	Dodecyl Benzene Sulfonic acid	Proprietary	27176-87-0	M	L	W	55	30	55	250	Gal	365	E	1	4	F			I	D	1-18
				Heavy Aromatic Slovent Naphtha	Proprietary	64742-94-5																		
				Naphthalene	Proprietary	91-20-3																		
1-18	CORR	135	Neutronex 309 Gold Plating Bath	Water	<95%	7732-18-5	M	L	W	15	10	15	60	Gal	365	E	1	4						1-18
				Tetrapotassium Pyrophosphate	<5%	7320-34-5																		
				Sodium Gold Sulfite	<2%	19153-98-1																		
				Thallium	<0.5%	Proprietary																		
1-18	CORR	135	Metex L5-B	Thiourea	10%	62-56-6	M	L	W	15	10	15	20	Gal	365	E	1	4				I	D	1-18
							Total			140				Gal										
1-23	FL	214	Mixed Solvent Waste	Acetone	10-30%	67-64-1	M	L	W	55	55	55	1004	Gal	365	D	1	4	F			I	D	1-23
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	10-30%	872-50-4																		
				Toluene	5-20%	108-88-3																		
				Xylene	1-10%	1130-20-7																		
				n-Butyl Acetate	1-10%	123-86-4																		
				Propylene Glycol Monomethyl ether acetate	1-10%	108-65-6																		
				Gamma Butrylactone	1-5%	872-50-4																		
				Chorolbenzene	1-5%	108-90-7																		
							Total			55				Gal										
1-33	FL	214	Mixed Solvent Waste	Acetone	10-30%	67-64-1	M	L	W	10	5	10	See Waste 1 23	Gal	365	G	1	4	F					1-33
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	5-20%	872-50-4																		
				Xylene	5-20%	1130-20-7																		
				Isoparaffinic Hydrocarbon	5-20%	64742-48-9																		
				n-Butyl Acetate	5-20%	123-86-4																		
				Propylene Glycol Monomethyl ether acetate	1-10%	108-65-6																		
							Total			10				Gal										
1-37	FL	214	Mixed Solvent Waste	Acetone	5-20%	67-64-1	M	L	W	10	5	10	See Waste 1 23	Gal	365	G	1	4	F					1-37
				Isopropyl Alcohol	10-30%	67-63-0																		
				n-Methyl Pyrrolidone	30-50%	872-50-4																		
							Total			10														
1-37	CORR	135	Metex L5-B	Thiourea	10%	62-56-6	M	L	W	1	1	1	20	Gal	365	R	1	5				I	D	1-37
							Total			1														
1-38	CL	214	Mixed Solvent Waste	Toluene	10-30%	108-88-3	M	L	W	10	5	10	See Waste 1-23	Gal	365	G	1	4	F			I	D	1-38
				Xylene	10-30%	1130-20-7																		
				Propylene Glycol Monomethyl ether acetate	50-70%	108-65-6																		
				Methyl 3-Methoxypropionate	1-5%	9/3/3852																		
				Chorolbenzene	1-2%	108-90-7																		
				Ethyl Lactate	1-5%	97-64-3																		
							Total			10				Gal										

Universal Semiconductor Technology, Inc- Aboveground Inventory Statement

Storage Location	DOT Class	CA Waste Code	Trade Name	Chemical Name	Conc%	CAS#	Physical State		V/W	Quantity		Max Cont Size	Annual Thru-put	Units	Days on Site	Storage			SARA Class					Storage Location
										Max	Avg					Type	Press	Temp	F	P	R	I	D	
1-37	NR		Fomblin Y-LVAC	Propene,1,1,2,3,3-hexafluoro	100%	69991-67-9	P	L	V	5	3	5		Gal	365	L	1	4				I		1-37
							Total			5				Gal										
1-38	CL		MICROPOSIT S1808 Photo Resist (NOWPAC)	Propylene Glycol Monomethyl ether acetate	65 - 90%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Cresol novolak resin	<30%																			
				Cresol	<0.9%	1319-77-3																		
				Diazo photoactive comp.	1 - 10%																			
				Fluoroaliphatic Polymer Esters	< 1 %	11114-17-3																		
1-38	CL		Positive Photo Resist AZ1529 (NOWPAC)	1-Methoxy-2-propanol acetate	66%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Cresol-novolak resin	<30%	117520-84-0																		
1-38	CL		AZ EBR Solvent	Propylene Glycol Monomethyl ether acetate	100%	108-65-6	M	L	V	5	3	5		Gal	365	F	2	4	F			I	D	1-38
1-38	CL		JSR IX875 Positive Photo Resist (NOWPAC)	Methyl 3-Methoxypropionate	75-85%	108-65-6	M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Phenolic Resin	10-20%	Proprietary																		
1-38	CL		MEGAPOSIT SPR 220 Photo Resist (NOWPAC)	Cresol novolak resin	25 - 30%		M	L	V	1	1	1		Gal	365	N	1	4	F			I	D	1-38
				Ethyl Lactate	25 - 35%	97-64-3																		
				Anisole	10 -20 %	100-66-3																		
				Diazo photoactive comp.	1 - 10 %																			
				2- Methlyl Butyl Acetate	1 -10 %	624-41-9																		
				n-amyl acetate	1 -10 %	628-63-7																		
				Cresol	< 1 %	1319-77-3																		
				Organic Siloxane Surfactant	< 1 %																			
							Total			9				Gal										
1-38	FL		Adhesion Promoter(Arch)	Hexamethyldisilazane	100%	999-97-3	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I		1-38
1-38	FL		495 PMMA Series Resist In Chlorobenzene	Monochlorobenzene	88 - 99%	108-90-7	M	L	V	0.25	0.25	0.25		Gal	365	M	1	4	F			I	D	1-38
				Poly (methylmerhacrylate)	1 -12 %	9011-14-7																		
1-38	FL		Toluene	Toluene	92%	108-88-3	P	L	V	1	0.5	1		Gal	365	R	1	4	F			I	D	1-38
1-38	FL		Xylene	Xylene	100%	1330-20-7	P	L	V	1	0.5	1		Gal	365	R	1	4	F					1-38
							Total			2.5				Gal										
1-38	NR		Fomblin Y-LVAC	Propene,1,1,2,3,3-hexafluoro	100%	69991-67-9	P	L	V	5	3	5		Gal	365	L	1	4				I		1-38
1-38	NR		MF-319 Developer	Tetramethyl Ammonium Hydroxide	2%	75-59-2	M	L	V	5	3	5		Gal	365	F	2	4				I		1-38
							Total			10				Gal										
1-38	OXY		Oxygen	Oxygen	100%	7782-44-7	P	G	V	337	200	337		CF	365	L	2	4	F	P				1-38
							Total			337				CF										
1-39	NFG		Nitrogen	Nitrogen	100%	7727-37-9	P	G	V	304	150	304		CF	365	L	2	4		P				1-39
							Total			304				CF										
1-39	FL		2-Propanol	Isopropy l Alcohol	100%	67-63-0	P	L	V	30.5	0.25	3 oz		Gal	365	N	1	4	F					1-39
1-39	FL		Acetone	Acetone	100%	67-64-1	P	L	V	30.5	0.25	3 oz		Gal	365	N	1	4	F					1-39
							Total			1				Gal										